

PCT/EP01/02 MAY 2002

**DECLARATION FOR PATENT APPLICATION (JOINT OR SOLE)**

(Under 37 CFR § 1.63; with Power of Attorney)

FROMMER LAWRENCE &amp; HAUG LLP

10/019203  
FLH File No. 450117-03703

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention ENTITLED:

**END-CAPPED POLYFLUORENES, FILMS AND DEVICES BASED THEREON**

the specification of which

is attached hereto.

X was filed on 20 April 2001 as International Application Serial No. PCT/EP01-04522,

with amendment(s) through \_\_\_\_\_ (if applicable, give dates).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

**Prior Foreign Application(s) [list additional applications on separate page]: Priority Claimed:**

Number:	Country:	Filed (Day/Month/Year):	Yes	No
00108877.2	Europe	26 April 2000	X	
PCT/EP01-04522	PCT	20 April 2001	X	

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application:

**Prior U.S. Application(s) [list additional applications on separate page]:****Appl. Ser. Number: Filed (Day/Month/Year): Status (patented, pending, abandoned):**

I hereby appoint WILLIAM S. FROMMER, Registration No. 25,506, and DENNIS M. SMID, Registration No. 34,930 or their duly appointed associate, my attorneys, with full power of substitution and revocation, to prosecute this application, to make alterations and amendments therein, to file continuation and divisional applications thereof, to receive the Patent, and to transact all business in the Patent and Trademark Office and in the Courts in connection therewith, and specify that all communications about the application are to be directed to the following correspondence address:

WILLIAM S. FROMMER, Esq.  
c/o FROMMER LAWRENCE & HAUG LLP  
745 Fifth Avenue  
New York, New York 10151

Direct all telephone calls to:  
(212) 588-0800  
to the attention of:  
WILLIAM S. FROMMER

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

INVENTOR(S):

Signature:

Full name of sole or first inventor:

Residence:

Citizenship:

P.O. Address:

Akio YASUDA

Date: 6/12/01

Stuttgart, Germany

Germany

c/o Advanced Technology Center Stuttgart

SONY International (Europe) GmbH

Heinrich-Hertz-Strasse 1

70327 Stuttgart, GERMANY

WDX

Signature:

Full name of 2nd joint inventor (if any):

Wolfgang KNOLL

Date: 10/16/01

Residence:

Citizenship:

P.O. Address:

Mainz, Germany

Germany

c/o Max-Planck-Institut für Polymerforschung

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55128 Mainz, GERMANY

WDX

(Similarly list additional inventors on separate page)

Post Office Address(es) of inventor(s):

[If all inventors have the same post office address]

Note: A post office address must be provided for each inventor.

## ADDITIONAL INVENTORS

Signature: Andreas Meisel Date: 12/07/2001

3W  
Full name of 3rd joint inventor (if any): Andreas MEISEL  
Residence: Frankfurt/Main, Germany  
Citizenship: Germany  
P.O. Address: c/o Max-Planck-Institut für Polymerforschung  
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55128 Mainz, GERMANY DSK

Signature: \_\_\_\_\_ Date: \_\_\_\_\_

Full name of 4th joint inventor (if any): Tzenka MITEVA  
Residence: Stuttgart, Germany  
Citizenship: Germany  
P.O. Address: c/o Advanced Technology Center Stuttgart  
SONY International (Europe) GmbH  
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70327 Stuttgart, GERMANY

Signature: Dieter Neher Date: 19.12.2001

Full name of 5th joint inventor (if any): Dieter NEHER  
Residence: Potsdam, Germany  
Citizenship: Germany  
P.O. Address: c/o Max-Planck-Institut für Polymerforschung  
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55128 Mainz, GERMANY DSK

Signature: \_\_\_\_\_ Date: \_\_\_\_\_

Full name of 6th joint inventor (if any): Heinz-Georg NOTHOFER  
Residence: Stuttgart, Germany  
Citizenship: Germany  
P.O. Address: c/o Advanced Technology Center Stuttgart  
SONY International (Europe) GmbH  
Heinrich-Hertz-Strasse 1  
70327 Stuttgart, GERMANY

Signature: Ulrich Scherf Date: 19.12.2001

Full name of 7th joint inventor (if any): Ulrich SCHERF  
Residence: Golm, Germany  
Citizenship: Germany  
P.O. Address: c/o Max-Planck-Institut für Polymerforschung  
Ackermannweg 10  
55128 Mainz, GERMANY DSK

32 MAY 2002

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 c/o FROMMER LAWRENCE & HAUG LLP  
 745 Fifth Avenue  
 New York, New York 10151

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 to the attention of:  
 WILLIAM S. FROMMER

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

**INVENTOR(S):**

Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
 Full name of sole or first inventor: Akio YASUDA  
 Residence: Stuttgart, Germany  
 Citizenship: Germany  
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Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
 Full name of 2nd joint inventor (if any): Wolfgang KNOLL  
 Residence: Mainz, Germany  
 Citizenship: Germany  
 P.O. Address: c/o Max-Planck-Institut für Polymerforschung  
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[Similarly list additional inventors on separate page]  
 Post Office Address(es) of inventor(s):  
 [if all inventors have the same post office address]

Note: A post office address must be provided for each inventor.

## ADDITIONAL INVENTORS

3W Signature: Andreas Meisel Date: 12/07/2001  
Full name of 3rd joint inventor (if any): Andreas MEISEL

Residence: Frankfurt/Main, Germany  
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Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Full name of 5th joint inventor (if any): Dieter NEHER

Residence: Germany  
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Signature: Heinz G. Notthoer Date: 20/12/2001  
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Full name of 7th joint inventor (if any): Ullrich SCHERF

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